

This document was generated on 10/01/2021

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number: 0739447017

Status: Active

Overview: HDM Backplane Connector System

Description: HDM Board-to-Board Backplane Header, Vertical, SMC, Solder Tail, Guide Pin Option,

Guide Post Location A, Polarizing Key Position N/A, 144 Circuits

Documents:

3D ModelProduct Specification PS-73670-9999-001 (PDF)3D Model (PDF)Packaging Specification PK-70873-0818-001 (PDF)

Drawing (PDF)

RoHS Certificate of Compliance (PDF)

Agency Certification

CSA LR19980 UL E29179

General

Product Family Backplane Connectors

Series <u>73944</u>
Application Backplane
Component Type PCB Header

Overview HDM Backplane Connector System

Product Name HDM

UPC 800755031096

Physical

Stackable

Surface Mount Compatible (SMC)

Circuits (Loaded) 144
Circuits (maximum) 144

Color - Resin Black, Natural

Durability (mating cycles max)

First Mate / Last Break

Flammability

Guide to Mating Part

Keying to Mating Part

Yes

Material - Metal Phosphor Bronze, Stainless Steel

Material - Plating Mating Gold Material - Plating Termination Tin

Material - Resin High Temperature Thermoplastic

Nο

No

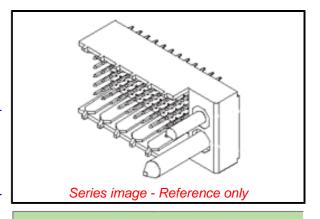
Net Weight 8.594/g Number of Columns 24

Number of Pairs Open Pin Field

Number of Rows 6
Orientation Vertical

PC Tail Length 3.50mm PCB Locator Yes **PCB** Retention None PCB Thickness - Recommended 2.50mm Packaging Type Tube Pitch - Mating Interface 2.00mm Pitch - Termination Interface 2.00mm Plating min - Mating 0.762µm Plating min - Termination 2.540um Polarized to PCB No

Temperature Range - Operating -55° to +105°C
Termination Interface: Style Through Hole



EU ELV

Not Relevant

EU RoHS China RoHS

Compliant REACH SVHC Not Contained Per -D(2020)9139-DC (19

Jan 2021)

<u>Halogen-Free</u>

<u>Status</u>

Low-Halogen

For more information, please visit Contact US

China ROHS Green Image
ELV Not Relevant
RoHS Phthalates Not Contained

Search Parts in this Series

73944 Series

Mates With

73632 HDM+ Board-to-Board Daughtercard Receptacle. 73780 HDM Board-to-Board

Daughtercard Receptacle

Application Tooling | FAQ

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

DescriptionProduct #Extraction Tool621001000

Electrical

Current - Maximum per Contact 1.0A
Data Rate 1.0 Gbps
Shielded No
Voltage - Maximum 250V AC

Solder Process Data

Duration at Max. Process Temperature (seconds) 040

Lead-freeProcess Capability SMC&WAVE

Max. Cycles at Max. Process Temperature 003
Process Temperature max. C 260

Material Info

Reference - Drawing Numbers

Packaging Specification PK-70873-0818-001 Product Specification PS-73670-9999-001

Sales Drawing SD-73944-001-001, SD-73944-001-002

This document was generated on 10/01/2021

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for High Speed/Modular Connectors category:

Click to view products by Molex manufacturer:

Other Similar products are found below:

650827-1 74040-1346 1410191-1 1410337-1 1410368-3 1410964-2 1410326-3 1410367-3 1410971-4 1467833-1 2000877-1 2000878-1 2041314-1 2065387-1 2187307-1 163P 1934290-1 2000875-1 2065917-1 2102736-2 FSR-40 2169868-2 22354-8 437-5040-000 5-1393565-0 039-0246-000 0761601016 0784461022 10123159-12ELF 030-2415-003/100 PK 030-7380-004 030-2494-001 532939-1 5532901-3 3-1469268-7 74748-102LF 73670-0247 10041743-101LF 10066670-100002LF 1-533915-1 249-4515-000 7-1469373-3 DL2-2J/S 2000713-8 2000713-7 10124313-101LF 3011-21 757105208 EBTF-4-10-2.0-S-RA-1 430305-001